

ABSTRACT OF THE DISCLOSURE

An electronic assembly including a die, having an integrated circuit formed therein, a thermally conductive heat spreader, and indium located between the die and the heat spreader, is described. The heat spreader has a layer of nickel. A gold layer is formed on the nickel layer, and provides better wetting of indium than nickel. A better structural connection between the indium and the heat spreader is provided, especially during thermal cycling.

For reference only